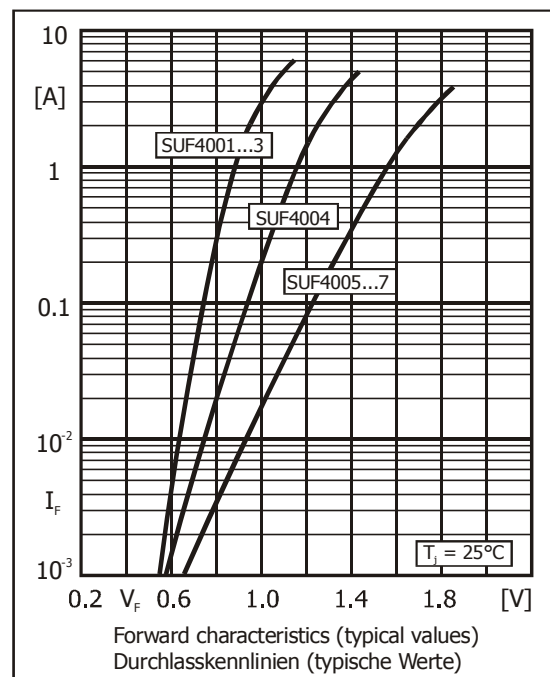
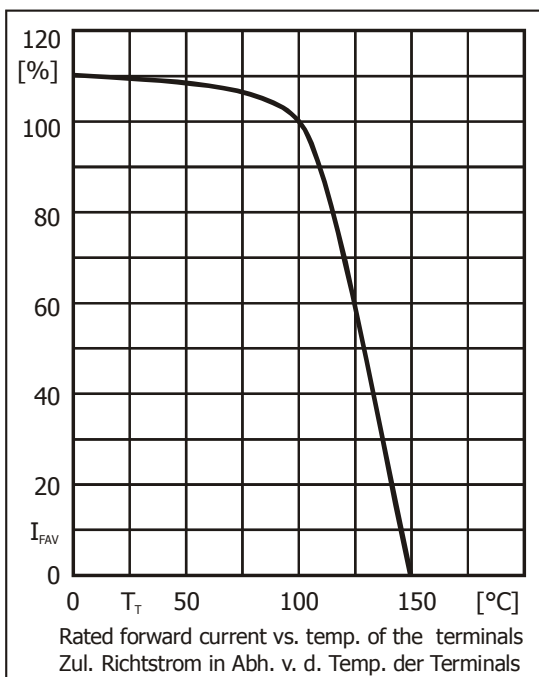


Characteristics
Kennwerte

| Type Typ | Reverse recovery time Sperrverzugszeit t_{rr} [ns] ¹⁾ | Forward voltage Durchlass-Spannung V_F [V] at / bei I_F [A] |
|-------------------|--------------------------------------------------------------------------|-----------------------------------------------------------------------|
| SUF4001...SUF4003 | < 50 | < 1.0 |
| SUF4004 | < 50 | < 1.25 |
| SUF4005...SUF4007 | < 75 | < 1.7 |

| | | | | |
|---------------------------------------------------------------------------------------------|-------------------------------------------------------|------------------------------------|----------------|-----------------------------------------|
| Leakage current Sperrstrom | $T_j = 25^\circ\text{C}$ $T_j = 100^\circ\text{C}$ | $V_R = V_{RRM}$ $V_R = V_{RRM}$ | I_R I_R | < 5 μA < 50 μA |
| Typical junction capacitance Typische Sperrschichtkapazität | | $V_R = 4\text{ V}$ | C_j | 10 pF |
| Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft | | | R_{thA} | < 45 K/W ²⁾ |
| Thermal resistance junction to terminal Wärmewiderstand Sperrschicht – Anschluss | | | R_{thT} | < 10 K/W |



Disclaimer: See data book page 2 or [website](#)
Haftungsausschluss: Siehe Datenbuch Seite 2 oder [Internet](#)

- $I_F = 0.5\text{ A}$ through/über $I_R = 1\text{ A}$ to/auf $I_R = 0.25\text{ A}$
- Mounted on P.C. board with 25 mm² copper pads at each terminal
Montage auf Leiterplatte mit 25 mm² Kupferbelag (Löt-pad) an jedem Anschluss